

AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS IN ASCENDING ORDER WITH STATUS INDICATOR

Please amend the following claims as indicated.

1. (Original) A thermoplastic resin composition containing 100 parts by weight of an amorphous thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermoplastic resin, characterized in that not less than 75% of the shape of a molded article is maintained at temperatures above the glass transition point of said thermoplastic resin.
2. (Original) A thermoplastic resin composition containing 100 parts by weight of an crystalline thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermoplastic resin, characterized in that not less than 75% of the shape of a molded article is maintained at temperatures above the melting point of said thermoplastic resin.
3. (Original) The thermoplastic resin composition according to claim 1 or 2, wherein the dispcrsion particle diameter of said inorganic compound is 2 μm or less.
4. (Currently Amended) The thermoplastic resin composition according to ~~any one of claims 1 to 3~~ claim 1 or 2, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as a constituent element.
5. (Currently Amended) The thermoplastic resin composition according to ~~any one of claims 1 to 4~~ claim 1 or 2, wherein said inorganic compound is laminar silicate.
6. (Currently Amended) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition according to ~~any one of claims 1 to 5~~ claim 1 or 2.

7. (Currently Amended) A film for substrates, characterized in that said film is composed by using the thermoplastic resin composition according to ~~any one of claims 1 to 5~~ claim 1 or 2.

8. (New) The thermoplastic resin composition according to claim 3, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as a constituent element.

9. (New) The thermoplastic resin composition according to claim 3, wherein said inorganic compound is laminar silicate.

10. (New) The thermoplastic resin composition according to claim 4, wherein said inorganic compound is laminar silicate.

11. (New) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition according to claim 3.

12. (New) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition according to claim 4.

13. (New) A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition according to claim 5.

14. (New) A film for substrates, characterized in that said film is composed by using the thermoplastic resin composition according to claim 3.

15. (New) A film for substrates, characterized in that said film is composed by using the thermoplastic resin composition according to claim 4.

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16. (New) A film for substrates, characterized in that said film is composed by using the thermoplastic resin composition according to claim 5.